TOSHIBA Field Effect Transistor Silicon N Channel MOS Type

# SSM3K01T

#### High Speed Switching Applications

- Small Package
- Low on Resistance:  $R_{on} = 120 \text{ m}\Omega \text{ (max)} (@V_{GS} = 4 \text{ V})$ :  $R_{on} = 150 \text{ m}\Omega \text{ (max)} (@V_{GS} = 2.5 \text{ V})$
- Low Gate Threshold Voltage:  $V_{th} = 0.6 \sim 1.1 \text{ V}$ (@VDS = 3 V, ID = 0.1 mA)

#### Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rating	Unit	
Drain-Source voltage		V <sub>DS</sub>	30	V	
Gate-Source voltage		V <sub>GSS</sub>	±10	V	
Drain current	DC	ID	3.2	А	
	Pulse	I <sub>DP</sub> (Note2)	6.4		
Drain power dissipation (Ta = $25^{\circ}$ C)		P <sub>D</sub> (Note1)	1250	mW	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	

1. GATE 2. SOURCE 3. DRAIN JEDEC — JEITA — TOSHIBA 2-3S1A

Weight: 10 mg (typ.)

2.9±0.2 1.9±0.2 0.95 | 0.95

Note1: Mounted on FR4 board

 $(25.4 \text{ mm} \times 25.4 \text{ mm} \times 1.6 \text{ t}, \text{ Cu pad: } 645 \text{ mm}^2, \text{ t} = 10 \text{ s})$ 

Note2: The pulse width limited by max channel temperature.

#### **Handling Precaution**

When handling individual devices (which are not yet mounted on a circuit board), be sure that the environment is protected against electrostatic electricity. Operators should wear anti-static clothing, and containers and other objects that come into direct contact with devices should be made of anti-static materials.

The Channel-to-Ambient thermal resistance  $R_{th}$  (ch-a) and the drain power dissipation PD vary according to the board material, board area, board thickness and pad area, and are also affected by the environment in which the product is used. When using this device, please take heat dissipation fully into account.

Unit: mm

£±0.

0.16±0.05

 $2.8^{+0.2}_{-0.3}$ 

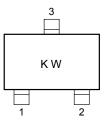
 $1.6^{+0.2}_{-0.1}$ 

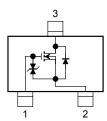
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### Marking

#### **Equivalent Circuit**



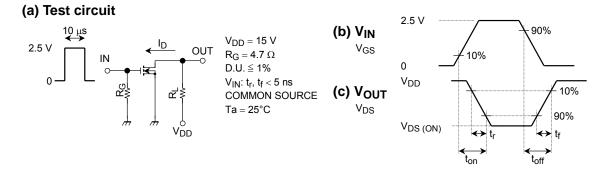


### Electrical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		IGSS	$V_{GS}=\pm 10~V,~V_{DS}=0$	_		±1	μA
Drain-Source breakdown voltage		V (BR) DSS	$I_D = 1 \text{ mA}, V_{GS} = 0$	30		_	V
Drain Cut-off current		I <sub>DSS</sub>	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0$	_	_	1	μA
Gate threshold voltage		V <sub>th</sub>	$V_{DS} = 3 \text{ V}, \text{ I}_{D} = 0.1 \text{ mA}$	0.6		1.1	V
Forward transfer admittance		Y <sub>fs</sub>	$V_{DS} = 3 V, I_D = 1.6 A$ (Note3)	2.6	5.2		S
Drain-Source ON resistance		R <sub>DS (ON)</sub>	$I_D = 1.6 \text{ A}, V_{GS} = 4 \text{ V}$ (Note3)	_	85	120	mΩ
Drain-Source ON resistance		R <sub>DS (ON)</sub>	$I_D = 1.3 \text{ A}, V_{GS} = 2.5 \text{ V}$ (Note3)	_	115	150	mΩ
Input capacitance		C <sub>iss</sub>	$V_{DS} = 10 \text{ V}, \text{ V}_{GS} = 0, \text{ f} = 1 \text{ MHz}$	_	152		pF
Reverse transfer capacitance		C <sub>rss</sub>	$V_{DS} = 10 \text{ V}, \text{ V}_{GS} = 0, \text{ f} = 1 \text{ MHz}$	_	41		pF
Output capacitance		C <sub>oss</sub>	$V_{DS} = 10 \text{ V}, \text{ V}_{GS} = 0, \text{ f} = 1 \text{ MHz}$	_	102		pF
Switching time	Turn-on time	t <sub>on</sub>	$V_{DD} = 15 \text{ V}, \text{ I}_{D} = 0.5 \text{ A}$	_	45		nS
	Turn-off time	t <sub>off</sub>	$V_{GS}$ = 0~2.5 V, $R_{G}$ = 4.7 $\Omega$	_	69	_	

Note3: Pulse test

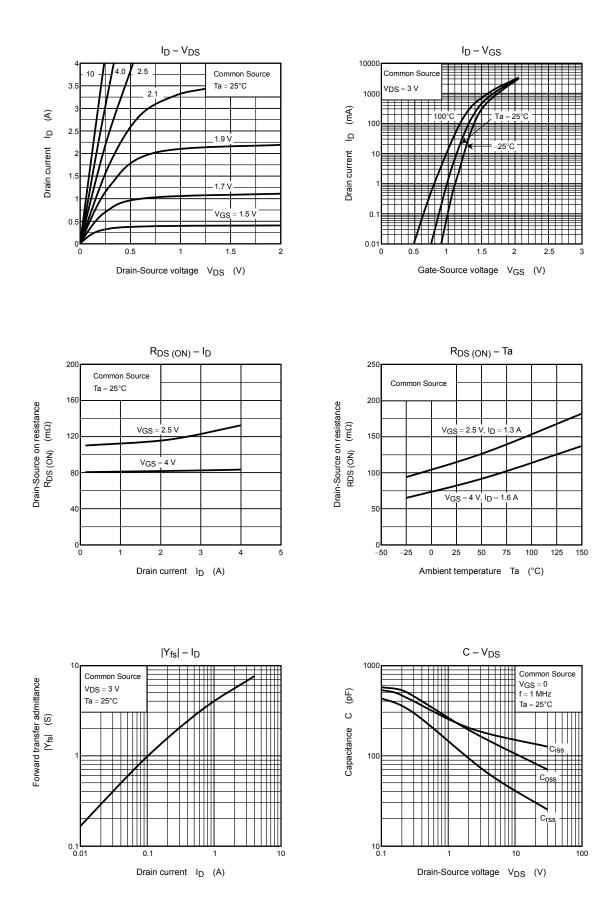
## **Switching Time Test Circuit**



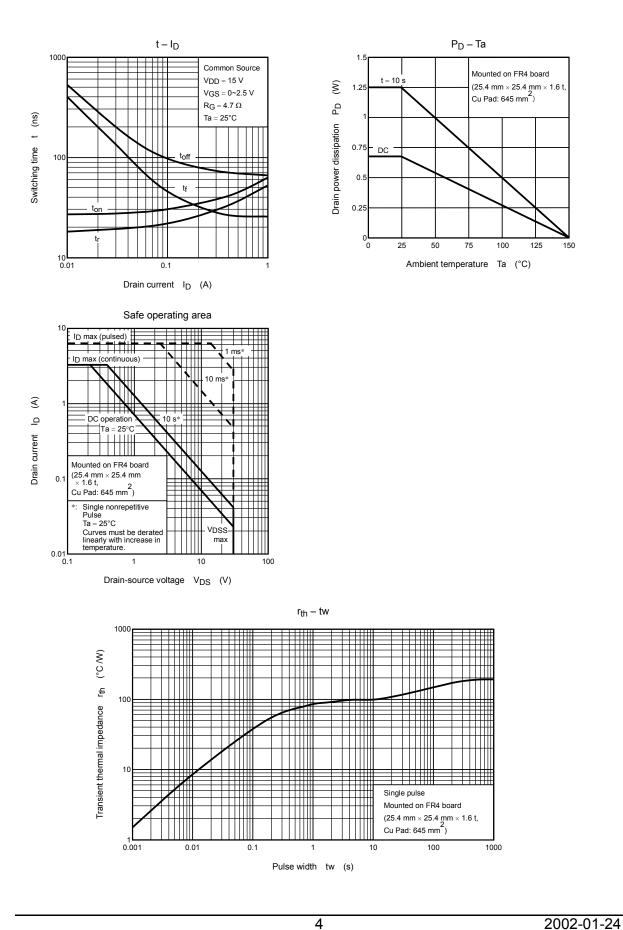
### Precaution

- $V_{th}$  can be expressed as voltage between gate and source when low operating current value is ID = 100  $\mu A$  for this product. For normal switching operation,  $V_{GS}$  (on) requires higher voltage than  $V_{th}$  and  $V_{GS}$  (off) requires lower voltage than  $V_{th}$ .
  - (relationship can be established as follows: VGS (off) < Vth < VGS (on))
  - $Please \ take \ this \ into \ consideration \ for \ using \ the \ device.$
  - $\mathrm{VGS}$  recommended voltage of 2.5 V or higher to turn on this product.

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